

**PART SPECIFICATION FOR APPROVAL**

<b>CUSTOMER</b>	<b>Aruba Networks</b>
<b>MODEL</b>	<b>EMSA120300-P5RP-SZ-C2</b>
<b>DESCRIPTION</b>	<b>switching power supply</b>
<b>DATE</b>	<b>05/26/2016</b>
<b># OF PAGES</b>	<b>26</b>

<b>rev.</b>	<b>description</b>	<b>date</b>
1.0	initial release	07/25/2014
1.01	updated to show CUI logo	08/06/2014
1.02	changed dc plug, updated part number	08/15/2014
1.03	added MTBF data	09/18/2014
1.04	increased operating temperature, decreased output current	10/14/2014
1.05	updated max output information	11/03/2014
1.06	updated safety labels	05/12/2015
1.07	updated safety and packaging labels	07/17/2015
1.08	added dc plug specification details	09/01/2015
1.09	updated PSE mark on safety label	11/04/2015
1.10	updated label	05/26/2016

The revision history provided is for informational purposes only and is believed to be accurate.

Please sign below.

approved by \_\_\_\_\_  
(please print)

signature \_\_\_\_\_

date \_\_\_\_\_

Specification sign-off verifies that you have reviewed the entire specification and tested this product and that it meets your requirements. This specification reflects the part as it is to be ordered. Orders will not be processed until the specification approval page has been signed and returned to CUI Inc. This specification is confidential and is not to be distributed without prior approval from CUI Inc.

MODEL	output voltage typ (Vdc)	output current <sup>1</sup> max (A)	output power <sup>1</sup> max (W)	ripple and noise <sup>2</sup> max (mVp-p)	efficiency level
EMSA120300-P5RP-SZ-C2	12	3.0	36	290	V

Notes:

1. Output is 2.5A max at 50°C
2. At full load, 100 ~ 240 Vac input, 20 MHz bandwidth oscilloscope
3. CX1: 0.33µF/275V (334) ±10% 13X14X8.0mm P=10mm  
BD1: KBP206G 2A/600V KBP LITEON  
CS8: SMD 1206 0.01 µF/630V (103)X7R

## INPUT

parameter	conditions/description	min	typ	max	units
voltage		90		264	Vac
frequency		47		63	Hz
input current				1.0	A
leakage current				0.25	mA
no load power consumption				0.3	W

## OUTPUT

parameter	conditions/description	min	typ	max	units
line regulation			±1		%
load regulation			±5		%

## PROTECTIONS

parameter	conditions/description	min	typ	max	units
over voltage protection	output voltage clamped by internal protection zener				
short circuit protection	output shut down and auto restart				

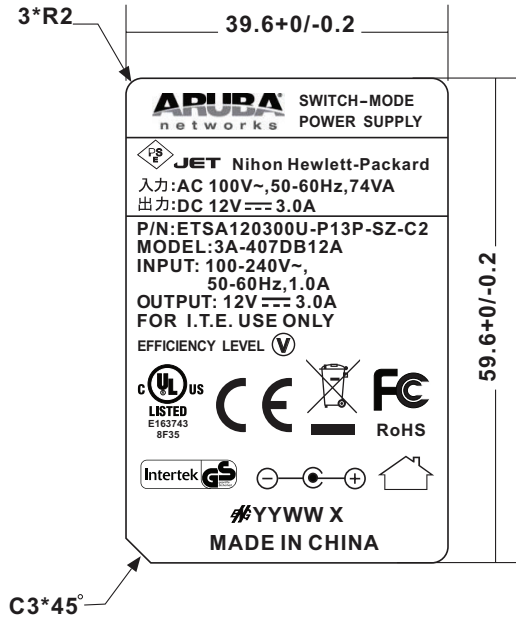
## SAFETY & COMPLIANCE

parameter	conditions/description	min	typ	max	units
isolation voltage	input to output for 1 minute at 10mA			3,000 4,242	Vac Vdc
insulation resistance	input to output at 500 Vdc	100			MΩ
safety approvals	UL/cUL, GS, RCM, CCC, PSE, Korea, Argentina, Brazil, Israel, Malaysia, Mexico, Russia, Saudi Arabia, Singapore, Taiwan, Ukraine, South Africa				
EMI/EMC	FCC class B, CE, VCCI				
RoHS	2011/65/EU				

## ENVIRONMENTAL

parameter	conditions/description	min	typ	max	units
operating temperature	derates from full load at 40°C to 2.5A at 50°C	0		50	°C
storage temperature		-10		70	°C
operating humidity		20		80	%
storage humidity		10		90	%

**LABEL**



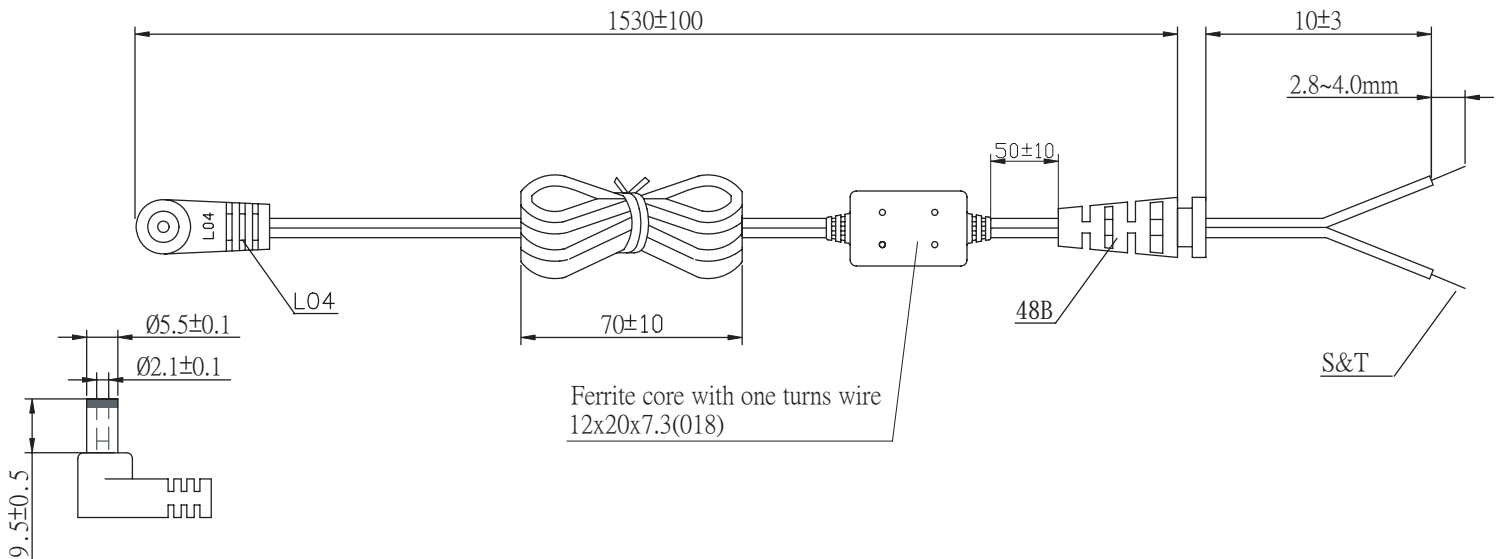
material: metalized polyester  
 color: silver on black base

remarks: YYWW X  
 YY=production year  
 WW=production week  
 X=production location



engraved

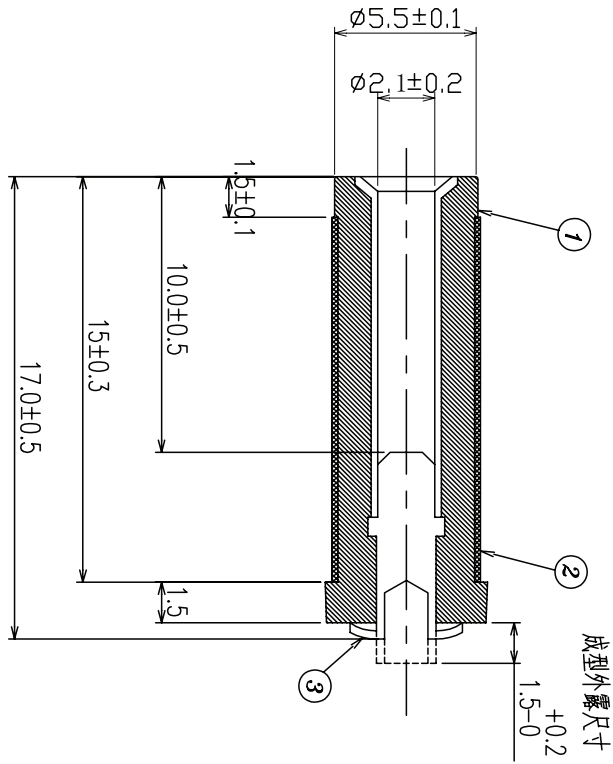
**DC CORD**



#18AWGX2C UL2468 WORDING ON WIRE (-), NO WORDING ON WIRE (+)

OD: Ø2.2\*4.4

DC PLUG

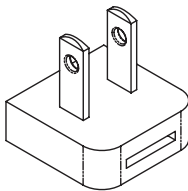
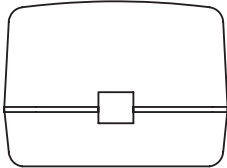
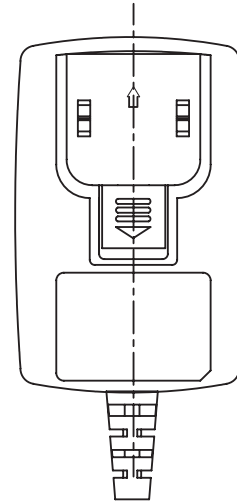
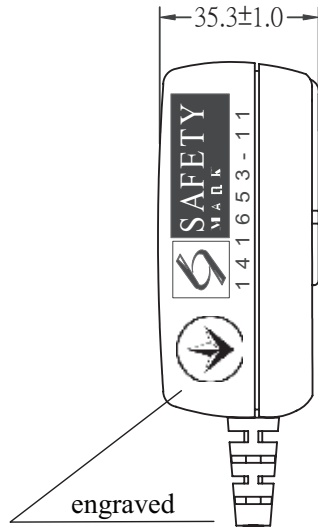
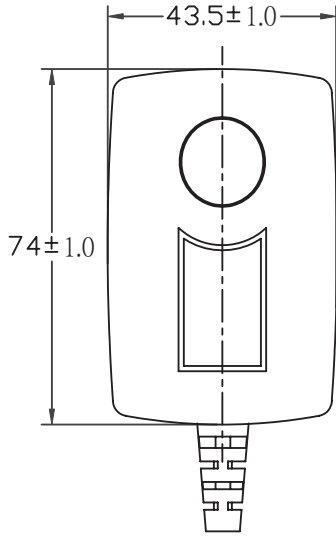


MARK	REVISION	DATE	SIGN	APPD17
△				

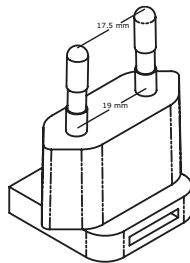
一般公差	單位	7							DATE
尺寸區分	mm	6							07/30/08
0以下, 0以下	公差	5							UNIT
		4							mm
1.0以下, 6.0以下		3	P-BRONZE	NICKEL	2um 以上				SCALE
6.0以下, 18.0以下		2	BRASS	NICKEL	2um 以上				4 : 1
18.0以下, 40.0以下		1	PPM	BLACK					EDITION
40.0以上		ND	MATERIAL	PLATING	THICKNESS				V1.0
承認		檢圖		設計		繪圖			
APPROVED BY		CHECKED BY		DESIGNED BY		DRAWN BY			
鵬德		鵬德		P/N : 5521170					
				DRAWN NO:					

## MECHANICAL DRAWING

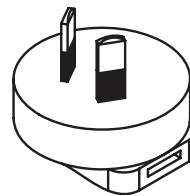
input plug	interchangeable blade: US, EU, UK, Australia, China, Korea, Brazil, Argentina
weight	272.4 g w/ blades
case size	74 L x 43.5 W x 35.3 H mm tolerance: ±1 mm



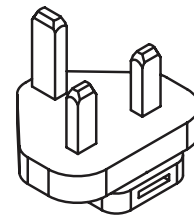
N. AMERICA



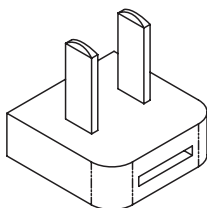
EU  
Ø4.0 mm



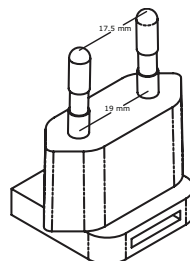
AUSTRALIA/  
NEW ZEALAND



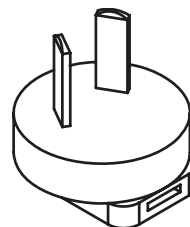
UK



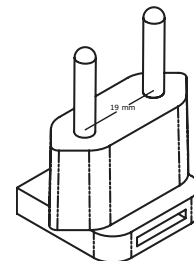
CHINA



KOREA  
Ø4.8 mm



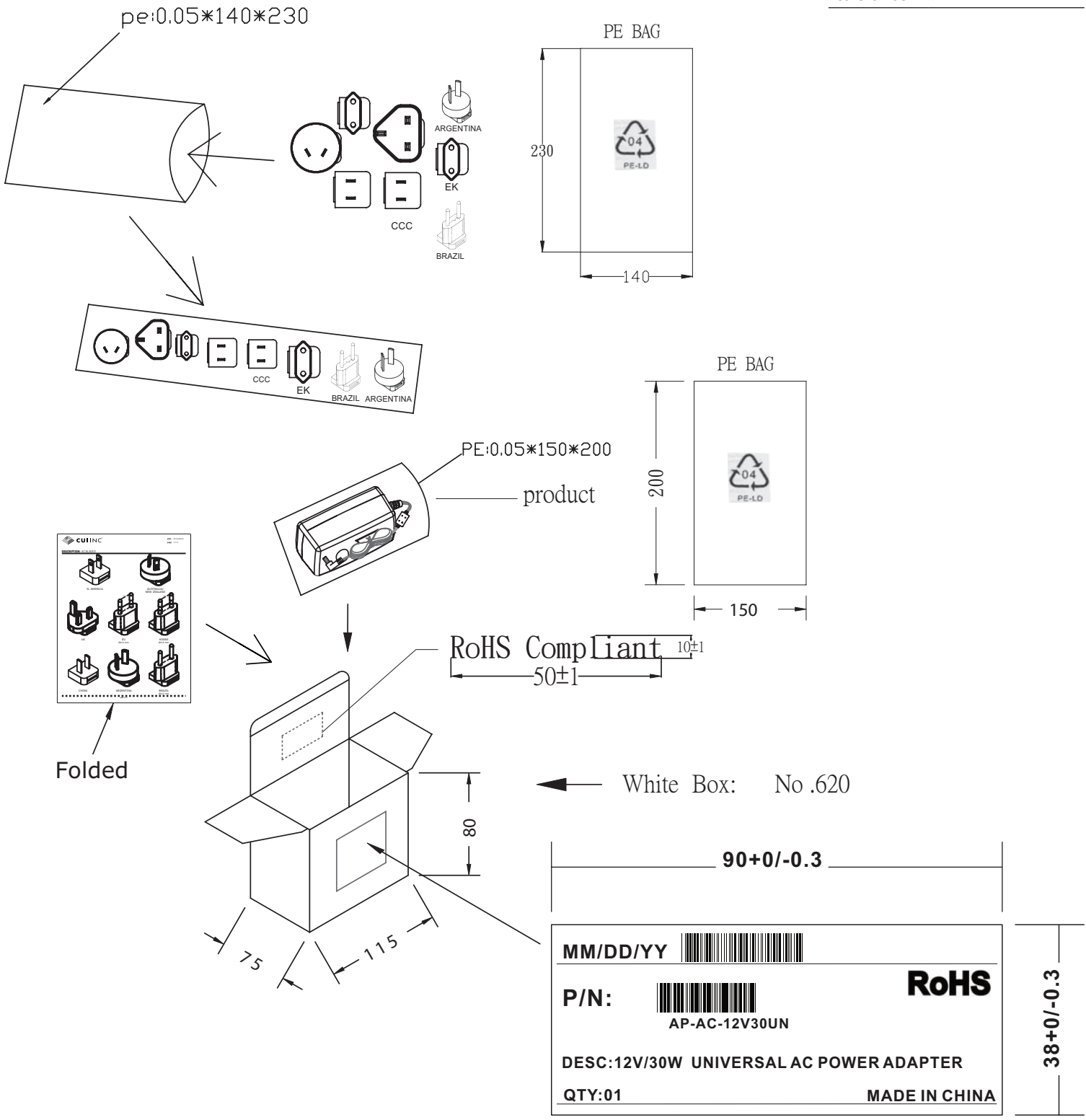
ARGENTINA



BRAZIL  
Ø4.0 mm

IND PACKAGING

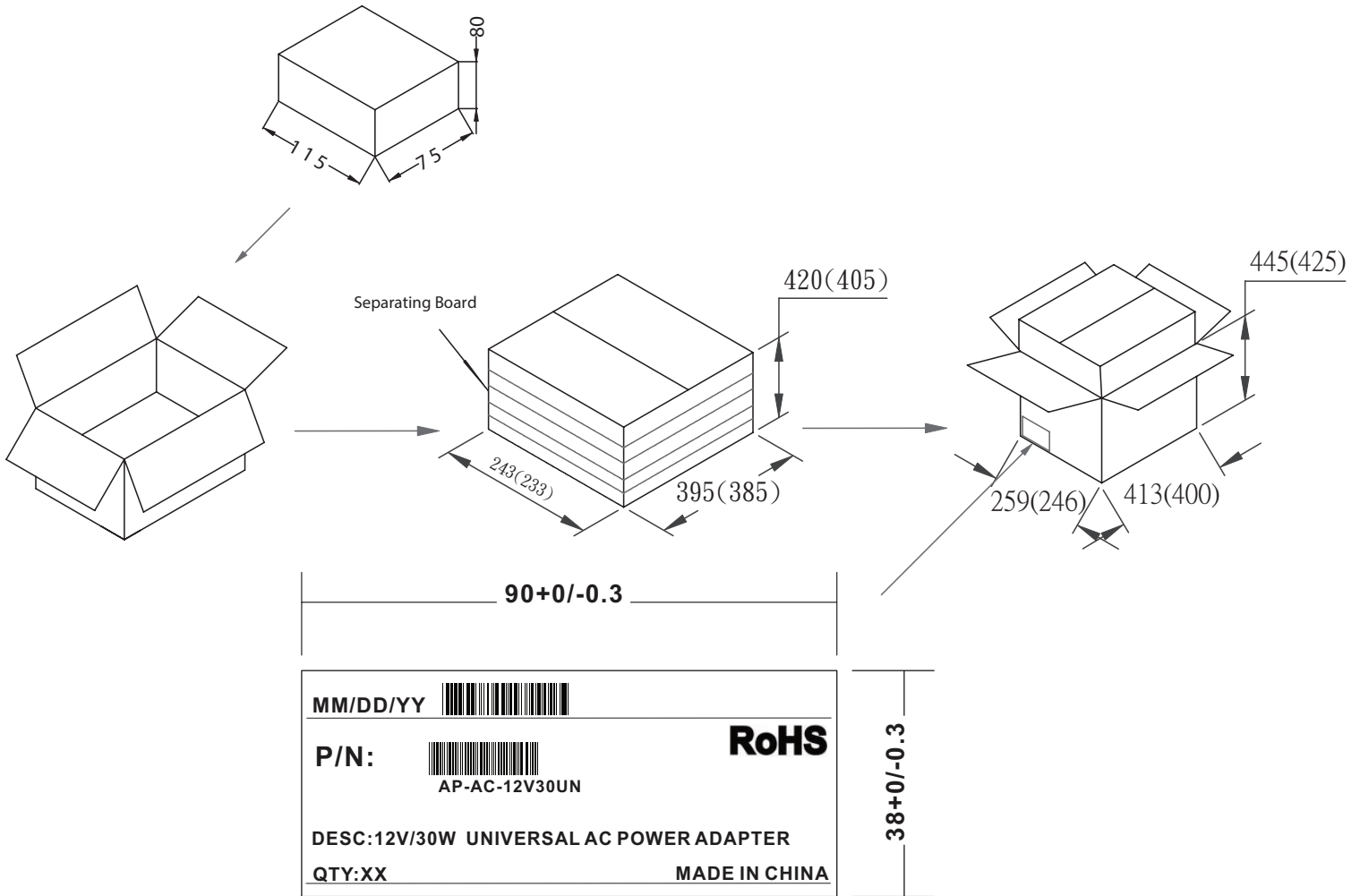
tolerance ±1 mm



## PACKAGING

External Carton Material: A=B (6mm)  
 Internal Carton Material: B3B (3mm)  
 Carton Size: 413 x 259 x 445mm  
 QTY: 50 pcs (10 x 5)  
 N.W: 13.62 KGS  
 G.W: 15.12 KGS  
 G.W: 15.62 KGS

tolerance	+7/-0 mm
-----------	----------



**MTBF (90 VAC, 50 °C)**

*TYPE : MTBF*

*REV :*

*TEST CONDITION*

*AC INPUT : 90V*

*ROOM TEMPERATURE : 50 °C*

*DC OUTPUT : 12V/2.5A*

<i>TYPE</i>	<i><math>\pi p</math></i>
RESISTOR	0.893873667
CERAMIC	0.024192688
PLASTIC CAPACITOR	0.010684965
CAPACITOR(ALUMINUM)	5.584212958
DIODE	1.479169536
MOSFET	1.067799075
IC	1.442706021
CHOKE	0.286458913
TRANSFORMER	1.455022943
FUSE NTC	0.02
PCB	0.32
LED PHOTO	0.161542033

**TOTAL  $\pi p$  = 12.7456628**

**MTBF = 78458 Hours 8.9564 Year**



**MTBF (90 VAC, 50 °C)**

**TYPE : Resister**  
**TEST CONDITION**  
**AC INPUT : 90V**  
**DC OUTPUT : 12V/2.5A**

**SPECIFICATION:**  
**ROOM TEMPERATURE : 50 °C**

P / N	Item	ohm	(W)	V <sub>m</sub>	$\pi_m$	S	T	$\pi_b$	$\pi_R$	$\pi_Q$	$\pi_E$	$\pi_P$	
	R2	1000000	0.5	90	0.0081	0.0162	90.78	0.001570733	1.1	5	2	0.017278059	DIP
	RS1	1	0.25	0.173	0.0299	0.119716	118.98	0.005412105	1	5	2	0.054121047	SMD
	RS2	1	0.25	0.173	0.0299	0.119716	121.35	0.005890175	1	5	2	0.058901747	SMD
	RS3	4.7	0.25	0.173	0.0064	0.025471489	120.29	0.004522847	1	5	2	0.045228474	SMD
	RS4	750000	0.25	42.16	0.0024	0.009479817	109.4	0.002971669	1.1	3	2	0.019613013	SMD
	RS8	750000	0.25	42.16	0.0024	0.009479817	110.54	0.003092788	1.1	5	2	0.03402067	SMD
	RS5	82000	0.25	57.38	0.0402	0.16060802	108.73	0.004128208	1	5	2	0.041282082	SMD
	RS6	82000	0.25	57.26	0.0400	0.159936956	109.98	0.004311267	1	5	2	0.043112672	SMD
	RS9	82000	0.25	57.26	0.0400	0.159936956	109.18	0.004189002	1	5	2	0.041890015	SMD
	RS10	82000	0.25	57.26	0.0400	0.159936956	110.17	0.004340826	1	5	2	0.043408259	SMD
	RS7	22	0.25	0.33	0.0050	0.0198	109.03	0.003004849	1	5	2	0.030048491	SMD
	RS17	82	0.25	0.142	0.0002	0.00098361	102.67	0.002302042	1	5	2	0.023020418	SMD
	RS18	82	0.25	0.142	0.0002	0.00098361	102.28	0.00227084	1	5	2	0.0227084	SMD
	RS14	2	0.25	0.012	0.0001	0.000288	104.23	0.002427304	1	5	2	0.024273039	SMD
	RS11	470	0.125	0.034	0.0000	0.0000196766	102.78	0.002305815	1	5	2	0.023058149	SMD
	RS12	100000	0.125	0.4	0.0000	0.0000128	103.83	0.002392056	1	5	2	0.023920557	SMD
	RS15	150	0.125	0.63	0.0026	0.021168	100.78	0.00225629	1	5	2	0.022562904	SMD
	RS16	100000	0.125	7.48	0.0006	0.004476032	100.4	0.002143258	1	5	2	0.021432584	SMD
	RS19	1000	0.125	0.986	0.0010	0.007777568	102.97	0.002362896	1	5	2	0.023628962	SMD
	RS24	1000	0.125	12.15	0.1476	1.18098	88.33	0.018821489	1	5	2	0.188214887	SMD
	RS20	430	0.125	0.569	0.0008	0.00602346	104.41	0.002475132	1	5	2	0.024751323	SMD
	RS21	18000	0.125	9.25	0.0048	0.038027778	104.97	0.00271762	1	5	2	0.027176201	SMD
	RS29	4650	0.125	2.45	0.0013	0.010326882	98.29	0.002017205	1	5	2	0.020172046	SMD
	RS28	4700	0.125	0.216	0.0000	0.0000794145	98.78	0.002004967	1	5	2	0.020049669	SMD
<b>Total <math>\pi_P</math> =</b>		<b>0.893873667</b>											

$\pi_m$  : Operating Power  
 S : Ratio of Operating Power to Rated Power  
 ( S=P<sub>m</sub>/P )  
 T : Component Temperature  
 $\pi_b$  : Base Failure Rate  
 (  $\pi_b = 4.5 \times 10^{-9} \exp(12((T+273)/343)) \exp(S/0.6((T+273)/273))$  )

$\pi_R$  : Resistance Factor  
 $\pi_Q$  : Quality Factor  
 $\pi_E$  : Environment Factor  
 $\pi_p = \text{AbPRPQPE Failures} / 10^6 \text{ Hours}$





**MTBF (90 VAC, 50 °C)**

**TYPE : Aluminum Capacitor**  
**TEST CONDITION**  
**AC INPUT : 90V**  
**DC OUTPUT : 12V/2.5A**

**SPECIFICATION:**  
**ROOM TEMPERATURE : 50 °C**

P / N	Item	(uF)	( V )	Vrip	Vp	S	T	$\pi b$	$\pi CV$	$\pi Q$	$\pi E$	$\pi P$	
	C1	68	400	39.4	111	0.41605	100	0.699911	0.726659	3	1	1.5258	105 °C
	C2	10	35	0.38	19.1	0.56066	101	0.863162	0.514611	3	1	1.3326	105 °C
	C3	470	25	0.71	12.2	0.52645	96.6	0.521068	1.029098	3	1	1.6087	105 °C
	C4	470	25	0.2	12.2	0.49709	92	0.361856	1.029098	3	1	1.1172	105 °C

**Total  $\pi P =$  5.584212958**

VP :Peak Voltage  $\pi Q$  : Quality Factor  
 S : Ratio of Peak to rated Voltage  $\pi E$  : Environment Factor  
 T : Component Temperature  $\pi p = \pi bPcvPQPE$  Failures / 10<sup>6</sup> Hours  
 $\pi b$  : Base Failure Rate (85 °C)  $\pi b$  : Base Failure Rate (105 °C)  
 $\pi b = (0.00254((S/0.5)^3+1)\exp(5.09((T+273)/378))^5$   $\pi b = (0.00254((S/0.5)^3+1)\exp(5.09((T+273)/378))^5$   
 $\pi cv$  : Capacitance Factor

**MTBF (90 VAC, 50 °C)**

**TYPE : Diode**

**TEST CONDITION**

**AC INPUT : 90V**

**ROOM TEMPERATURE : 50 °C**

**DC OUTPUT : 12V/2.5A**

P / N	Item	(V)	(A)	VP	S	T <sub>j</sub>	π <sub>b</sub>	π <sub>T</sub>	π <sub>S</sub>	π <sub>C</sub>	π <sub>Q</sub>	π <sub>E</sub>	π <sub>P</sub>
	BD1	600	2	140	0.233333	112	0.003	4.30201	0.0291	2	5.5	6	0.0248
	D1	1000	1.5	266	0.266	110	0.069	4.19386	0.04	2	5.5	6	0.76466
	D2	200	1	37.8	0.189	107	0.069	4.01354	0.0175	2	5.5	6	0.31895
	D3	60	20	31.4	0.523333	102	0.003	3.75045	0.2073	2	5.5	6	0.15395
	DS1	75	0.15	12.4	0.165333	102	0.069	3.77622	0.0126	2	5.5	6	0.2168

**Total π<sub>P</sub> = 1.479169536**

V<sub>m</sub> : Voltage Applied

π<sub>S</sub> : Electrical Stress Factor

S : Stress = V<sub>m</sub>/V

π<sub>c</sub> : Contact Construction Factor

T : Component Temperature

π<sub>Q</sub> : Quality Factor

π<sub>b</sub> : Base Failure Rate

π<sub>E</sub> : Environment Factor

π<sub>T</sub> : Temperature Factor

π<sub>p</sub> = AbPTPSPCPQPE Failures / 10<sup>6</sup> Hours

=exp(-1925((1/(T+273))-(1/298)))

SCR PT : Temperature Factor

SCR PR(P<sub>c</sub>) : Current Rating Factor

=exp(-3082((1/(T+273))-(1/298)))

= (I<sub>rms</sub>)<sup>0.40</sup>

**MTBF (90 VAC, 50 °C)**

**TYPE : MOSFET**  
**TEST CONDITION**  
**AC INPUT : 90V**  
**DC OUTPUT : 12V/2.5A**

**SPECIFICATION:**  
**ROOM TEMPERATURE : 50 °C**

P / N	Item	V	V <sub>op</sub>	S	T	$\pi_b$	$\pi_T$	$\pi_A$	$\pi_Q$	$\pi_E$	$\pi_P$	
	Q1	600	317	0.528333	107	0.012	4.04469	4	5.5	1	1.067799	DIP

**Total  $\pi_P = 1.067799075$**

V<sub>m</sub> :Max Voltage  
 T : Component Temperature  
 $\pi_b$  : Base Failure Rate  
 $\pi_T$  : Temperature Facto  
 $=\exp(-1925((1/(T+273))-(1/298)))$   
 $\pi_A$  : Application Factor

$\pi_Q$  : Quality Factor  
 $\pi_E$  : Environment Factor  
 $\pi_p = AbPTPAPQPE \text{ Failures} / 10^6 \text{ Hours}$

**MTBF (90 VAC, 50 °C)**

**TYPE : IC**

**TEST CONDITION**

**AC INPUT : 90V**

**DC OUTPUT : 12V/2.5A**

**SPECIFICATION:**

**ROOM TEMPERATURE : 50 °C**

P / N	Item	Part type	pin	S	T	C <sub>1</sub>	C <sub>2</sub>	$\pi T$	$\pi E$	$\pi Q$	$\pi L$	$\pi P$
	QS1		3		97.09	0.02	0.0030	13.85	2	2	1	0.566
	US1		8		105.36	0.02	0.0030	21.62	2	2	1	0.877

**Total  $\pi P = 1.442706021$**

T : Component Temperature

$\pi E$  : Environment Factor

C<sub>1</sub> : Die Complexity Failure Rates

$\pi Q$  : Quality Factor

C<sub>2</sub> : Package Failure Rate for all Microcircuits

$\pi L$  : Learning Factor

$\pi T$  : Temperature Factor

$\pi p = (C1PT + C2PE) PLPQ$  Failures / 10<sup>6</sup> Hours

**TYPE : Choke**

**TEST CONDITION**

**AC INPUT : 90V**

**DC OUTPUT : 12V/2.5A**

**SPECIFICATION:**

**ROOM TEMPERATURE : 50 °C**

P / N	Item	Spec	P <sub>m</sub>	S	T	$\pi b$	$\pi c$	$\pi Q$	$\pi E$	$\pi P$	
	LF1				98.61	0.0011	1	30	4	0.1267	DIP
	LF2				106.23	0.0013	1	30	4	0.1597	DIP

**Total  $\pi P = 0.286458913$**

T : Component Temperature

$\pi b$  : Base Failure Rate

$$(Ab = 0.000319 \exp(((T+273)/364)^{8.7}))$$

$\pi c$  : Construction Factor

$\pi Q$  : Quality Factor

$\pi E$  : Environment Factor

$\pi p = AbPCPQPE$  Failures / 10<sup>6</sup> Hours

**MTBF (90 VAC, 50 °C)**

**TYPE : Transformer**

**SPECIFICATION:**

**TEST CONDITION**

**AC INPUT : 90V**

**ROOM TEMPERATURE : 50 °C**

**DC OUTPUT : 12V/2.5A**

P / N	Item	Spec	$\pi_m$	S	T	$\pi_b$	$\pi_Q$	$\pi_E$	$\pi_P$	
	T1				105.25	0.008083	30	6	1.4550229	DIP

**Total  $\pi_P =$  1.455022943**

T : Component Temperature

$\pi_b$  : Base Failure Rate

$\pi_Q$  : Quality Factor

$\pi_E$  : Environment Factor

$\pi_p$  : AbPQPE Failures / 10<sup>6</sup> Hours

**TYPE : Fuse**

**SPECIFICATION:**

**TEST CONDITION**

**AC INPUT : 90V**

**ROOM TEMPERATURE : 50 °C**

**DC OUTPUT : 12V/2.5A**

P / N	Item	V	A	$\pi_m$	S	$\pi_Q$	$\pi_b$	$\pi_E$	$\pi_P$	
	FS1	250	2				0.01	2	0.02	DIP

**Total  $\pi_P =$  0.02**

T : Component Temperature

$\pi_b$  : Base Failure Rate

$\pi_E$  : Environment Factor

$\pi_p$  : AbPE Failures / 10<sup>6</sup> Hours



**MTBF (90 VAC, 50 °C)**

**TYPE : PCB**  
**TEST CONDITION**  
**AC INPUT : 90V**  
**DC OUTPUT : 12V/2.5A**

**SPECIFICATION:**  
**ROOM TEMPERATURE : 50 °C**

P / N	Item	Spec	T	$\pi_b$	N1	N2	$\pi_c$	$\pi_Q$	$\pi_E$	$\pi_P$
	PCB	94-V0	107.96	0.0008	200	0	1	2	1	0.32

**Total  $\pi_P =$  0.32**

$\pi_b$  : Base Failure Rate  
 N1,N2 : Number of PTHS Factor  
 $\pi_c$  : Complexity Factor  
 $\pi_Q$  : Quality Factor  
 $\pi_E$  : Environment Factor  
 $\pi_p = \pi_b((N1 \times PC + N2(PC + 13)))PQPE$  Failures /  $10^6$  Hours

**TYPE : LED PHOTO**  
**TEST CONDITION**  
**AC INPUT : 90V**  
**DC OUTPUT : 12V/2.5A**

**SPECIFICATION:**  
**ROOM TEMPERATURE : 50 °C**

P / N	Item	Spec	T	$\pi_b$	$\pi_T$	$\pi_Q$	$\pi_E$	$\pi_P$
	U1		94.5	0.0025	5.8743	5.5	2	0.1615

**Total  $\pi_P =$  0.161542033**

$\pi_b$  : Base Failure Rate  
 $\pi_T$  : Complexity Factor  
 $\pi_Q$  : Quality Factor  
 $\pi_E$  : Environment Factor  
 $\pi_p = \pi_b * \pi_T * \pi_Q * \pi_E * \pi_P$  Failures /  $10^6$  Hours

**MTBF (264 VAC, 50 °C)**

*TYPE : MTBF*

*REV :*

*TEST CONDITION*

*AC INPUT : 264V*

*ROOM TEMPERATURE : 50 °C*

*DC OUTPUT : 12V/2.5A*

<i>TYPE</i>	<i><math>\pi p</math></i>
RESISTOR	0.89468301
CERAMIC	0.023815667
PLASTIC CAPACITOR	0.158717373
CAPACITOR(ALUMINUM)	10.10915038
DIODE	3.831811368
MOSFET	1.046323846
IC	1.540940061
CHOKE	0.210586034
TRANSFORMER	1.768622927
FUSE NTC	0.02
PCB	0.32
LED PHOTO	0.17371219

**TOTAL  $\pi p$  = 20.09836285**

**MTBF = 49755 Hours 5.679828 Year**

**MTBF (264 VAC, 50 °C)**

<b>TYPE : Resister</b>						<b>SPECIFICATION:</b>							
<b>TEST CONDITION</b>						<b>ROOM TEMPERATURE : 50 °C</b>							
<b>AC INPUT : 264V</b>													
<b>DC OUTPUT : 12V/2.5A</b>													
P / N	Item	ohm	(W)	Vm	$\pi_m$	S	T	$\pi_b$	$\pi_R$	$\pi_Q$	$\pi_E$	$\pi_P$	
	R2	1000000	0.5	264	0.0697	0.139392	89.37	0.001963262	1.1	5	2	0.021595882	DIP
	RS1	1	0.25	0.051	0.0026	0.010404	114.13	0.003515081	1	5	2	0.035150814	SMD
	RS2	1	0.25	0.051	0.0026	0.010404	116.44	0.003811511	1	5	2	0.038115111	SMD
	RS3	4.7	0.25	0.051	0.0006	0.002213617	114.98	0.003551799	1	5	2	0.035517995	SMD
	RS4	750000	0.25	167.03	0.0372	0.148794778	106.97	0.003770245	1.1	3	2	0.024883618	SMD
	RS8	750000	0.25	167.1	0.0372	0.14891952	109.12	0.004073908	1.1	5	2	0.044812987	SMD
	RS5	82000	0.25	55.96	0.0382	0.152757151	107.33	0.00385458	1	5	2	0.038545802	SMD
	RS6	82000	0.25	55.96	0.0382	0.152757151	108.23	0.00398122	1	5	2	0.0398122	SMD
	RS9	82000	0.25	55.96	0.0382	0.152757151	107.43	0.00386845	1	5	2	0.038684499	SMD
	RS10	82000	0.25	55.26	0.0372	0.148959395	109.58	0.004142118	1	5	2	0.041421185	SMD
	RS7	22	0.25	0.34	0.0053	0.021018182	108.21	0.00292787	1	5	2	0.029278701	SMD
	RS17	82	0.25	0.49	0.0029	0.011712195	112	0.003272268	1	5	2	0.032722678	SMD
	RS18	82	0.25	0.49	0.0029	0.011712195	110.81	0.003138564	1	5	2	0.031385645	SMD
	RS14	2	0.25	0.012	0.0001	0.000288	105.54	0.002541144	1	5	2	0.025411439	SMD
	RS11	470	0.125	0.035	0.0000	0.00002085106	102.43	0.002277759	1	5	2	0.022777586	SMD
	RS12	100000	0.125	2.11	0.0000	0.000356168	102.23	0.002263615	1	5	2	0.022636146	SMD
	RS15	150	0.125	0.587	0.0023	0.018377013	102.08	0.00234663	1	5	2	0.023466296	SMD
	RS16	100000	0.125	1.83	0.0000	0.000267912	100.78	0.002151208	1	5	2	0.021512079	SMD
	RS19	1000	0.125	0.99	0.0010	0.0078408	106.2	0.002646375	1	5	2	0.026463749	SMD
	RS24	1000	0.125	12.15	0.1476	1.18098	89.64	0.019891154	1	5	2	0.198911536	SMD
	RS20	430	0.125	0.603	0.0008	0.006764819	106.79	0.002694912	1	5	2	0.026949121	SMD
	RS21	18000	0.125	9.24	0.0047	0.0379456	106.11	0.002828409	1	5	2	0.02828409	SMD
	RS29	4650	0.125	2.45	0.0013	0.010326882	101.97	0.002294904	1	5	2	0.022949041	SMD
	RS28	4700	0.125	0.224	0.0000	0.00008540596	103.19	0.002339481	1	5	2	0.023394811	SMD
<b>Total <math>\pi_P</math></b>						<b>0.89468301</b>							
$\pi_m$ :Operating Power						$\pi_R$ : Resistance Factor							
S : Ratio of Operating Power to Rated Power ( S=Pm/P )						$\pi_Q$ : Quality Factor							
T : Component Temperature						$\pi_E$ : Environment Factor							
$\pi_b$ : Base Failure Rate ( $\pi_b = 4.5 \times 10^{-9} \exp(12((T+273)/343)) \exp(S/0.6((T+273)/273)$ )						$\pi_p = \text{AbPRPQPE Failures} / 10^6 \text{ Hours}$							

**MTBF (264 VAC, 50 °C)**

**TYPE : Ceramic**

**SPECIFICATION:**

**TEST CONDITION**

**AC INPUT : 264V**

**ROOM TEMPERATURE : 50 °C**

**DC OUTPUT : 12V/2.5A**

P / N	Item	(pF)	(V)	V <sub>P</sub>	S	T	A <sub>b</sub>	π <sub>CV</sub>	π <sub>Q</sub>	π <sub>E</sub>	π <sub>P</sub>	
	CY1	1000	400	80.5	0.20125	100	0.001108	0.876564	3	1	0.002913	DIP
	CS7	470	50	1.83	0.0366	100	0.000852	0.806705	3	1	0.002062	SMD
	CS1	2200	500	111	0.2225	106	0.001216	0.955983	3	1	0.003489	SMD
	CS4	100000	50	18.9	0.378	104	0.002581	1.454735	3	1	0.011263	SMD
	CS6	220000	50	8.01	0.1602	101	0.000984	1.586538	3	1	0.004682	SMD
	CS5	1000	200	12.2	0.06085	110	0.000882	0.876564	3	1	0.00232	SMD

**Total π<sub>P</sub> =** 0.023815667

V<sub>p</sub> :Peak Voltage

π<sub>E</sub> : Environment Factor

S : Ratio of Peak to rated Voltage

π<sub>p</sub> = AbP<sub>cv</sub>PQPE Failures / 10<sup>6</sup> Hours

( S=V<sub>p</sub>/V )

π<sub>Q</sub> : Quality Factor

T : Component Temperature

Ab : Base Failure Rate

$$Ab = (0.0003((S/0.3)^3 \exp((T+273)/358))$$

π<sub>cv</sub> : Capacitance Factor

**MTBF (264 VAC, 50 °C)**

**TYPE : Plastic Capacitor**  
**TEST CONDITION**  
**AC INPUT : 264V**  
**DC OUTPUT : 12V/2.5A**

**SPECIFICATION:**  
**ROOM TEMPERATURE : 50 °C**

P / N	Item	(uF)	(V)	V <sub>P</sub>	S	T	A <sub>b</sub>	π <sub>CV</sub>	π <sub>Q</sub>	π <sub>E</sub>	π <sub>P</sub>	
	CX1	220000	270	264	0.977778	90.4	0.029487	1.794215	3	1	0.158717	DIP

**Total π<sub>P</sub> =** 0.158717373

V<sub>p</sub> :Peak Voltage  
 S : Ratio of Peak to rated Voltage  
 ( S=V<sub>p</sub>/V )  
 T : Component Temperature  
 A<sub>b</sub> : Base Failure Rate  
 $A_b = (0.0003((S/0.3)^3 \exp((T+273)/358)))$   
 π<sub>cv</sub> : Capacitance Factor  
 π<sub>Q</sub> : Quality Factor  
 π<sub>E</sub> : Environment Factor  
 π<sub>p</sub> = A<sub>b</sub>P<sub>cv</sub>P<sub>Q</sub>P<sub>E</sub> Failures / 10<sup>6</sup> Hours

**TYPE : Aluminum Capacitor**  
**TEST CONDITION**  
**AC INPUT : 264V**  
**DC OUTPUT : 12V/2.5A**

**SPECIFICATION:**  
**ROOM TEMPERATURE : 50 °C**

P / N	Item	(uF)	( V )	V <sub>rip</sub>	V <sub>p</sub>	S	T	π <sub>b</sub>	π <sub>CV</sub>	π <sub>Q</sub>	π <sub>E</sub>	π <sub>P</sub>	
	C1	68	400	11.6	370	0.96576	99.8	2.545583	0.726659	3	1	5.5493	105 °C
	C2	10	35	0.37	18.9	0.55487	101	0.992772	0.514611	3	1	1.5327	105 °C
	C3	470	25	0.4	12.2	0.50925	99.6	0.595777	1.029098	3	1	1.8393	105 °C
	C4	470	25	0.15	12.2	0.49454	93.2	0.384748	1.029098	3	1	1.1878	105 °C

**Total π<sub>P</sub> =** 10.10915038

V<sub>P</sub> :Peak Voltage  
 S : Ratio of Peak to rated Voltage  
 T : Component Temperature  
 π<sub>b</sub> : Base Failure Rate (85 °C)  
 $\pi_b = (0.00254((S/0.5)^3 + 1) \exp(5.09((T+273)/378)))^5$   
 π<sub>cv</sub> : Capacitance Factor  
 π<sub>Q</sub> : Quality Factor  
 π<sub>E</sub> : Environment Factor  
 π<sub>p</sub> = π<sub>b</sub>P<sub>cv</sub>P<sub>Q</sub>P<sub>E</sub> Failures / 10<sup>6</sup> Hours  
 π<sub>b</sub> : Base Failure Rate (105 °C)  
 $\pi_b = (0.00254((S/0.5)^3 + 1) \exp(5.09((T+273)/378)))^5$

**MTBF (264 VAC, 50 °C)**

**TYPE : Diode**

**TEST CONDITION**

**AC INPUT : 264V**

**ROOM TEMPERATURE : 50 °C**

**DC OUTPUT : 12V/2.5A**

P / N	Item	(V)	(A)	VP	S	T <sub>j</sub>	$\pi_b$	$\pi_T$	$\pi_S$	$\pi_C$	$\pi_Q$	$\pi_E$	$\pi_P$
	BD1	600	2	408	0.68	100	0.003	3.68396	0.392	2	5.5	6	0.28574
	D1	1000	1.5	300	0.3	108	0.069	4.06951	0.054	2	5.5	6	0.99389
	D2	200	1	74.4	0.372	106	0.069	3.98199	0.09	2	5.5	6	1.64026
	D3	60	20	56.8	0.946667	104	0.003	3.89246	0.875	2	5.5	6	0.6746
	DS1	75	0.15	12.8	0.170667	103	0.069	3.82652	0.014	2	5.5	6	0.23731

**Total  $\pi_P = 3.831811368$**

V<sub>m</sub> : Voltage Applied

$\pi_S$  : Electrical Stress Factor

S : Stress = V<sub>m</sub>/V

$\pi_c$  : Contact Construction Factor

T : Component Temperature

$\pi_Q$  : Quality Factor

$\pi_b$  : Base Failure Rate

$\pi_E$  : Environment Factor

$\pi_T$  : Temperature Factor

$\pi_p = AbPTPSPCPQPE$  Failures / 10<sup>6</sup> Hours

$=\exp(-1925((1/(T+273))-(1/298)))$

SCR PT : Temperature Factor

SCR PR(P<sub>c</sub>) : Current Rating Factor

$=\exp(-3082((1/(T+273))-(1/298)))$

$= (I_{rms})^{0.40}$

**TYPE : MOSFET**

**SPECIFICATION:**

**TEST CONDITION**

**AC INPUT : 264V**

**ROOM TEMPERATURE : 50 °C**

**DC OUTPUT : 12V/2.5A**

P / N	Item	V	V <sub>op</sub>	S	T	$\pi_b$	$\pi_T$	$\pi_A$	$\pi_Q$	$\pi_E$	$\pi_P$
	Q1	600	576	0.96	106	0.012	3.96335	4	5.5	1	1.04632

**Total  $\pi_P = 1.046323846$**

V<sub>m</sub> :Max Voltage

$\pi_Q$  : Quality Factor

T : Component Temperature

$\pi_E$  : Environment Factor

$\pi_b$  : Base Failure Rate

$\pi_p = AbPTPAPQPE$  Failures / 10<sup>6</sup> Hours

$\pi_T$  : Temperature Facto

$=\exp(-1925((1/(T+273))-(1/298)))$

$\pi_A$  : Application Factor

**MTBF (264 VAC, 50 °C)**

**TYPE : IC**

**SPECIFICATION:**

**TEST CONDITION**

**AC INPUT : 264V**

**ROOM TEMPERATURE : 50 °C**

**DC OUTPUT : 12V/2.5A**

P / N	Item	Part type	pin	S	T	C <sub>1</sub>	C <sub>2</sub>	$\pi_T$	$\pi_E$	$\pi_Q$	$\pi_L$	$\pi_P$
	QS1		3		101.09	0.02	0.0030	17.22	2	2	1	0.701
	US1		8		104.54	0.02	0.0030	20.7	2	2	1	0.84

**Total  $\pi_P = 1.540940061$**

T : Component Temperature

$\pi_E$  : Environment Factor

C<sub>1</sub> : Die Complexity Failure Rates

$\pi_Q$  : Quality Factor

C<sub>2</sub> : Package Failure Rate for all Microcircuits

$\pi_L$  : Learning Factor

$\pi_T$  : Temperature Factor

$\pi_p = (C_1 \pi_T + C_2 \pi_E) \pi_L \pi_Q$  Failures / 10<sup>6</sup> Hours

**TYPE : Choke**

**SPECIFICATION:**

**TEST CONDITION**

**AC INPUT : 264V**

**ROOM TEMPERATURE : 50 °C**

**DC OUTPUT : 12V/2.5A**

P / N	Item	Spec	P <sub>m</sub>	S	T	$\pi_b$	$\pi_c$	$\pi_Q$	$\pi_E$	$\pi_P$	
	LF1				88.47	0.0008	1	30	4	0.0981	DIP
	LF2				94.15	0.0009	1	30	4	0.1125	DIP

**Total  $\pi_P = 0.210586034$**

T : Component Temperature

$\pi_b$  : Base Failure Rate

$$(Ab = 0.000319 \exp(((T+273)/364)^{8.7}))$$

$\pi_c$  : Construction Factor

$\pi_Q$  : Quality Factor

$\pi_E$  : Environment Factor

$\pi_p = Ab \pi_c \pi_Q \pi_E$  Failures / 10<sup>6</sup> Hours

**MTBF (264 VAC, 50 °C)**

<b>TYPE : Transformer</b>					<b>SPECIFICATION:</b>					
<b>TEST CONDITION</b>					<b>ROOM TEMPERATURE : 50 °C</b>					
<b>AC INPUT : 264V</b>										
<b>DC OUTPUT : 12V/2.5A</b>										
P / N	Item	Spec	$\pi_m$	S	T	$\pi_b$	$\pi_Q$	$\pi_E$	$\pi_P$	
	T1				110.98	0.009826	30	6	1.768623	DIP
<b>Total <math>\pi_P =</math></b>		<b>1.768622927</b>								
<p>T : Component Temperature  <math>\pi_b</math> : Base Failure Rate  <math>\pi_Q</math> : Quality Factor  <math>\pi_E</math> : Environment Factor  <math>\pi_p</math> : AbPQPE Failures / 10<sup>6</sup> Hours</p>										

<b>TYPE : Fuse</b>					<b>SPECIFICATION:</b>					
<b>TEST CONDITION</b>					<b>ROOM TEMPERATURE : 50 °C</b>					
<b>AC INPUT : 264V</b>										
<b>DC OUTPUT : 12V/2.5A</b>										
P / N	Item	V	A	$\pi_m$	S	$\pi_Q$	$\pi_b$	$\pi_E$	$\pi_P$	
	FS1	250	2				0.01	2	0.02	DIP
<b>Total <math>\pi_P =</math></b>		<b>0.02</b>								
<p>T : Component Temperature  <math>\pi_b</math> : Base Failure Rate  <math>\pi_E</math> : Environment Factor  <math>\pi_p</math> : AbPE Failures / 10<sup>6</sup> Hours</p>										



**MTBF (264 VAC, 50 °C)**

<b>TYPE : PCB</b>						<b>SPECIFICATION:</b>					
<b>TEST CONDITION</b>						<b>ROOM TEMPERATURE : 50 °C</b>					
<b>AC INPUT : 264V</b>											
<b>DC OUTPUT : 12V/2.5A</b>											
P / N	Item	Spec	T	$\pi_b$	N1	N2	$\pi_c$	$\pi_Q$	$\pi_E$	$\pi_P$	
	PCB	94-V0	107.84	0.0008	200	0	1	2	1	0.32	
<b>Total <math>\pi_P =</math></b>		<b>0.32</b>									
<p><math>\pi_b</math> : Base Failure Rate                  N1,N2 : Number of PTHS Factor  <math>\pi_c</math> : Complexity Factor  <math>\pi_Q</math> : Quality Factor  <math>\pi_E</math> : Environment Factor  <math>\pi_p = \pi_b((N1 \times PC + N2(PC + 13)))PQPE</math> Failures / <math>10^6</math> Hours</p>											

<b>TYPE : LED PHOTO</b>						<b>SPECIFICATION:</b>					
<b>TEST CONDITION</b>						<b>ROOM TEMPERATURE : 50 °C</b>					
<b>AC INPUT : 264V</b>											
<b>DC OUTPUT : 12V/2.5A</b>											
P / N	Item	Spec	T	$\pi_b$	$\pi_T$	$\pi_Q$	$\pi_E$	$\pi_P$			
	U1		98.05	0.0025	6.3168	5.5	2	0.1737	SMD		
<b>Total <math>\pi_P =</math></b>		<b>0.17371219</b>									
<p><math>\pi_b</math> : Base Failure Rate  <math>\pi_T</math> : Complexity Factor  <math>\pi_Q</math> : Quality Factor  <math>\pi_E</math> : Environment Factor  <math>\pi_p = \pi_b * \pi_T * \pi_Q * \pi_E * \pi_P</math> Failures / <math>10^6</math> Hours</p>											

## REVISION HISTORY

rev.	description	date
1.0	initial release	07/25/2014
1.01	updated to show CUI logo	08/06/2014
1.02	changed dc plug, updated part number	08/15/2014
1.03	added MTBF data	09/18/2014
1.04	increased operating temperature, decreased output current	10/14/2014
1.05	updated max output information	11/03/2014
1.06	updated safety labels	05/12/2015
1.07	updated safety and packaging labels	07/17/2015
1.08	added dc plug specification details	09/01/2015
1.09	updated PSE mark on safety label	11/04/2015
1.10	updated label	05/26/2016

The revision history provided is for informational purposes only and is believed to be accurate.



**CUI INC**<sup>®</sup>

**Headquarters**  
20050 SW 112th Ave.  
Tualatin, OR 97062  
**800.275.4899**

Fax 503.612.2383  
**cui.com**  
techsupport@cui.com

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

CUI offers a one (1) year limited warranty. Complete warranty information is listed on our website.

CUI reserves the right to make changes to the product at any time without notice. Information provided by CUI is believed to be accurate and reliable. However, no responsibility is assumed by CUI for its use, nor for any infringements of patents or other rights of third parties which may result from its use.

CUI products are not authorized or warranted for use as critical components in equipment that requires an extremely high level of reliability. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.